

TSMC-01-413

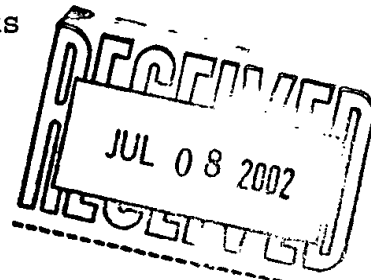


2812
#3
7-8-2

April 3, 2002

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603



Subject:

Serial No. 10/060,483 01/30/02

Yen-Ming Chen et al.

NOVEL METHOD TO IMPROVE BUMP
RELIABILITY FOR FLIP CHIP DEVICE

Grp. Art Unit: 2812

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on April 10, 2002.

Stephen B. Ackerman, Reg.# 3776

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SBA 4/10/02

U.S. Patent 5,543,253 to Park et al., "Photomask for T-Gate Formation and Process for Fabricating the Same," discusses a dual damascene like Photo process for a T-gate.

U.S. Patent 6,042,996 to Lin et al., "Method of Fabricating a Dual Damascene Structure," discusses a dual damascene process.

The following four U.S. Patents disclose Bump and UBM processes:

- 1) U.S. Patent 6,232,212 to Degani et al., "Flip Chip Bump Bonding."
- 2) U.S. Patent 6,153,503 to Lin et al., "Continuous Process for Producing Solder Bumps on Electrodes of Semiconductor Chips."
- 3) U.S. Patent 6,130,141 to Degani et al., "Flip Chip Metallization."
- 4) U.S. Patent 6,118,180 to Loo et al., "Semiconductor Die Metal Layout for Flip Chip Packaging."

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

(Use several sheets if necessary)

Attachment Number

10/060,483

Application to

Applicant: Yen-Ming Chen et al.

Filing Date

Filing Date 01/30/02

Group Art Unit

2812

U. S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTSOTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.